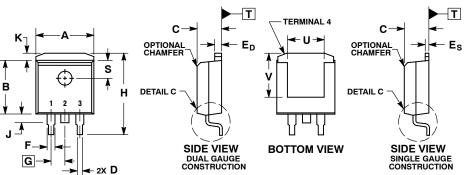
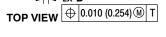
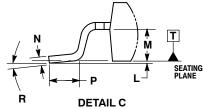


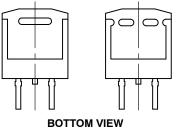
D²PAK CASE 936-03 ISSUE E

DATE 29 SEP 2015









OPTIONAL CONSTRUCTIONS

SOLDERING FOOTPRINT* - 10.490 8.380 16.155 3.504 2X 1.016 5.080 PITCH

DIMENSIONS: MILLIMETERS *For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCHES. TAB CONTOUR OPTIONAL WITHIN DIMENSIONS

- A AND K.
 DIMENSIONS U AND V ESTABLISH A MINIMUM
- MOUNTING SURFACE FOR TERMINAL 4.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH OR GATE PROTRUSIONS. MOLD FLASH AND GATE PROTRUSIONS NOT TO EXCEED 0.025 (0.635) MAXIMUM.
- SINGLE GAUGE DESIGN WILL BE SHIPPED AF-TER FPCN EXPIRATION IN OCTOBER 2011.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.386	0.403	9.804	10.236
В	0.356	0.368	9.042	9.347
С	0.170	0.180	4.318	4.572
D	0.026	0.036	0.660	0.914
ED	0.045	0.055	1.143	1.397
Es	0.018	0.026	0.457	0.660
F	0.051 REF		1.295 REF	
G	0.100 BSC		2.540 BSC	
Н	0.539	0.579	13.691	14.707
J	0.125 MAX		3.175 MAX	
K	0.050	REF	1.270 REF	
L	0.000	0.010	0.000	0.254
M	0.088	0.102	2.235	2.591
N	0.018	0.026	0.457	0.660
P	0.058	0.078	1.473	1.981
R	0°	8°	0°	8°
S	0.116	0.116 REF 2.946 REF		REF
U	0.200	MIN	5.080 MIN	
٧	0.250	MIN	6.350 MIN	

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code

= Assembly Location

= Wafer Lot 1 = Year Υ ww = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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